

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (CURRENTLY AMENDED) A process for fabricating a thin-film magnetic head having an air bearing surface ~~[[the]]~~ [[the]], the method comprising the unordered steps of:
 - (a) polishing ~~[[the]]~~ [[the]] a surface of a first side of a monolithic substrate wafer;
 - (b) forming ~~on the surface of the first side of the monolithic substrate wafer~~ a first array of magnetic read head structures and magnetic write head structures on the surface of the first side of the monolithic substrate wafer, each magnetic read head structure and magnetic write head structure having a head gap;
 - (c) polishing ~~[[the]]~~ [[the]] a surface of ~~[[the other]]~~ [[the other]] a second side of the monolithic substrate wafer;
 - (d) forming ~~on the surface of the other side of the monolithic substrate wafer~~ a second array of magnetic read head structures and magnetic write head structures on the surface of the second side of the monolithic substrate wafer, the second array of magnetic read head structures and magnetic write head structures disposed such that ~~a plurality of~~ the magnetic read head gaps on ~~[[one of]]~~ [[one of]] the first monolithic substrate ~~[[surfaces]]~~ surface are ~~[[each]]~~ aligned ~~to form a read/write track pair with a corresponding one of~~ with the magnetic write head gaps on the ~~[[other]]~~ [[other]] second monolithic substrate surface to form a read/write track-pair;
 - (e) cutting the monolithic substrate to expose the head gaps of a plurality of read/write track-pairs; and
 - (f) lapping the ~~[[the]]~~ [[the]] air bearing surface to refine the depth of the exposed head gaps.

2. (CURRENTLY AMENDED) The method of claim 1 wherein the ~~first and second arrays comprise:~~

~~a plurality of magnetic read and write head structures~~ first and second arrays of magnetic read head structures and magnetic write head structures are disposed such that each read head structure is covered by a collocated write head structure in a piggy-back configuration.

3. (ORIGINAL) The method of claim 2 wherein each of the magnetic read heads includes a magnetoresistive (MR) sensor element.

4. (CURRENTLY AMENDED) The method of claim 1 further comprising the step of:

(h) cutting the monolithic substrate to separate ~~[[therefrom]]~~ a thin-film magnetic head having a single read/write track-pair from the monolithic substrate.

5. (ORIGINAL) The method of claim 4 wherein each of the magnetic read heads includes a magnetoresistive (MR) sensor element.

6. (CANCELLED)

7. (ORIGINAL) The method of claim 1 wherein each of the magnetic read heads includes a magnetoresistive (MR) sensor element.

20. (WITHDRAWN) A process for fabricating a thin-film magnetic head having an air bearing surface (ABS), the method comprising the unordered steps of:

- (a) polishing the surface of a front side of a monolithic substrate wafer;
- (b) forming on the surface of the front side of the monolithic substrate wafer an array of magnetic read head structures and magnetic write head structures each having a head gap;

(c) sectioning the monolithic substrate wafer to form a plurality of wafer subsections each having a back surface;

(d) fixing the back surfaces of a pair of the wafer subsections to one another disposed such that a plurality of the magnetic read head gaps on the front surface of one of the wafer subsections are each aligned to form a read/write track-pair with a corresponding one of the magnetic write head gaps on the front surface of the other wafer subsection;

(e) cutting the fixed pair of wafer subsections to expose the head gaps of a plurality of read/write track-pairs; and

lapping the ABS to refine the depth of the exposed head gaps.

21. (WITHDRAWN) The method of claim 20 wherein the first and second arrays comprise:

a plurality of magnetic read and write head structures disposed such that each read head structure is covered by a collocated write head structure in a piggy-back configuration.

22. (WITHDRAWN) The method of claim 21 wherein each of the magnetic read heads includes a magnetoresistive (MR) sensor element.

23. (WITHDRAWN) The method of claim 20 further comprising the step of:

(h) cutting the fixed pair of wafer subsections to separate therefrom a thin-film magnetic head having a single read/write track-pair.

24. (WITHDRAWN) The method of claim 23 wherein each of the magnetic read heads includes a magnetoresistive (MR) sensor element.

25. (WITHDRAWN) The method of claim 20 wherein the array comprises a plurality of magnetic read head structures adjoining one another.

26. (WITHDRAWN) The method of claim 20 wherein each of the magnetic read heads includes a magnetoresistive (MR) sensor element.